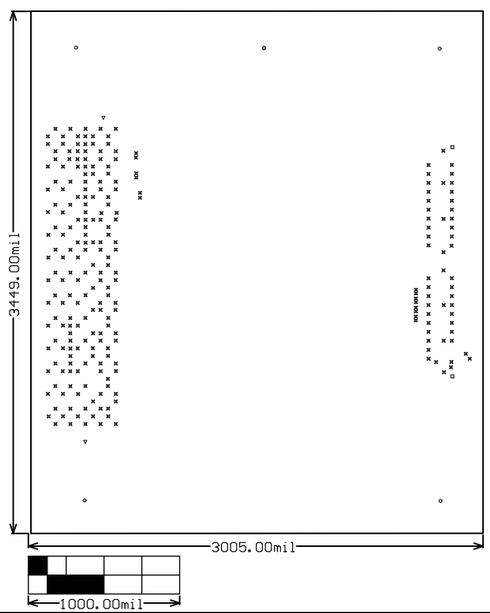
NOTE:

1. DIFFERENTIAL TRACES (5 MIL WIDTH AND GAP) ON L1, L4 AND L6 LAYERS ARE 100 OHMS +/- 10%
2. NON-DIFFERENTIAL TRACES (5 MIL WIDTH) ON L1, L4 AND L6 LAYERS ARE 50 OHMS +/- 10%

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.40mil		
4	Dielectric1	Isola370HR	5.00mil	4.8	
5	GND1	Copper	1.42mil		
6	Dielectric 2	Isola370HR	20.00mil	4.8	
7	GND2	Copper	1.42mil		
8	Dielectric 3	Isola370HR	5.00mil	4.8	
9	Signal Layer 1	Copper	1.42mil		
10	Dielectric 5	Isola370HR	20.00mil	4.8	
11	GND3	Copper	1.42mil		
12	Dielectric 4	Isola370HR	5.00mil	4.8	
13	Bottom Layer	Copper	1.40mil		
14	Bottom Solder	Solder Resist	0.40mil	3.5	
15	Bottom Overlay				

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
□	2	45.28mil (1.150mm)	NPTH	Round	Top Layer - Bottom Layer	
▽	2	50.00mil (1.270mm)	NPTH	Round	Top Layer - Bottom Layer	
⌘	244	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	
✪	1	63.00mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer	
○	4	125.98mil (3.200mm)	PTH	Round	Top Layer - Bottom Layer	
	253 Total					



DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 0.2 mm
MIN. VIA PAD SIZE: 24 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[ ] FR-408 [ ] FR-4 High Tg [X] OTHER Isola 370HR
THICKNESS: [X] 62 MIL +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [ ] GREEN [X] OTHER RED
[X] MATTE [ ] SEMI-GLOSS
SURFACE FINISH: [ ] IMMERSION GOLD (ENIG) [X] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER
ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER
ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
[ ] XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
[ ] XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
[ ] OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
[ ] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE: ADC35XX LVDS Interposer
DESIGNED FOR: Public Release
FILE NAME: ADC35XX_TSW1400_Interposer_PCB.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: 35XX_L_INT	REV: A	SVN REV: Not In VersionControl
LAYER NAME = [illegible]ions	TID #: N/A		
PLOT NAME = Fabrication Drawing	GENERATED : 7/7/2020 2:27:26 PM		TEXAS INSTRUMENTS

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ENGINEER: Daniel Brock
LAYOUT BY: Daniel Brock
SCALE: 1.00
ALTIUM DESIGNER VERSION: 18.1.9.240